

## 1.8MHz Zero-Drift CMOS Rail IO Opamp with

### **Features**

Single-Supply Operation from +1.8V ~ +5.5V

• Rail-to-Rail Input / Output

• Gain-Bandwidth Product: 1.8MHz (Typ@25°C)

Low Input Bias Current: 20pA (Typ@25°C)

Low Offset Voltage: 30µV (Max@25°C)

Zero Drift: 0.01µV/°C (Typ)

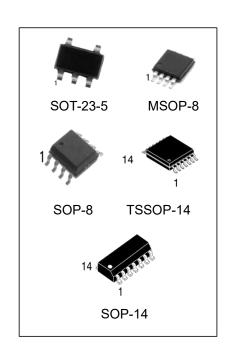
Quiescent Current: 180µA per Amplifier (Typ)

Operating Temperature: -40°C ~ +85°C

• Embedded RF Anti-EMI Filter

Small Package:

HGV8551 Available in SOT-23-5 and SOP-8 Packages HGV8552 Available in MSOP-8 and SOP-8 Packages HGV8554 Available in SOP-14 and TSSOP-14 Packages



### **Package/Ordering Information**

DEVICE	Package Type	MARKING	Packing	Packing Qty
HGV8551M5/TR	SOT-23-5	8551	REEL	3000pcs/reel
HGV8551M/TR	SOP-8	V8551	REEL	2500pcs/reel
HGV8552M/TR	SOP-8	V8552	REEL	2500pcs/reel
HGV8552MM/TR	MSOP-8	V8552	REEL	3000pcs/reel
HGV8554M/TR	SOP-14	HGV8554	REEL	2500pcs/reel
HGV8554MT/TR	TSSOP-14	V8554	REEL	2500pcs/reel



### **General Description**

The HGV855X amplifier is single/dual/quad supply, micro-power, zero-drift CMOS operational amplifiers, the amplifiers offer bandwidth of 1.8MHz, rail-to-rail inputs and outputs, and single-supply operation from 1.8V to 5.5V. HGV855X uses chopper stabilized technique to provide very low offset voltage (less than 30µV maximum) and near zero drift over temperature. Low quiescent supply current of 180µA per amplifier and very low input bias current of 20pA make the devices an ideal choice for low offset, low power consumption and high impedance applications. The HGV855X offers excellent CMRR without the crossover associated with traditional complementary input stages. This design results in superior performance for driving analog-to-digital converters (ADCs) without degradation of differential linearity. The HGV8551 is available in SOT-23-5 and SOP8 packages. And the HGV8552 is available in MSOP8 and SOP8 packages. The HGV8554 Quad is available in Green SOP14 and TSSOP14 packages. The extended temperature range of -40°C to +85°C over all supply voltages offers additional design flexibility.

#### **Applications**

- Transducer Application
- Temperature Measurements
- Electronics Scales
- Handheld Test Equipment
- Battery-Powered Instrumentatio

### **Pin Configuration**

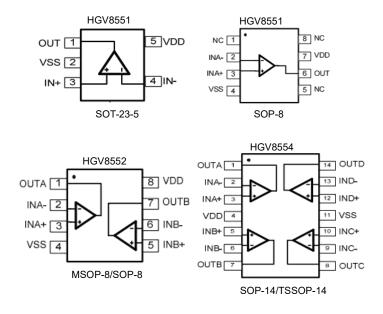


Figure 1. Pin Assignment Diagram

### **Absolute Maximum Ratings**

Condition	Min	Max			
Power Supply Voltage (V <sub>DD</sub> to Vss)	-0.5V	+7.5V			
Analog Input Voltage (IN+ or IN-)	Vss-0.5V	V <sub>DD</sub> +0.5V			
PDB Input Voltage	Vss-0.5V	+7V			
Operating Temperature Range	-40°C	+85°C			
Junction Temperature	+160°C				
Storage Temperature Range	-55°C	+150°C			
Lead Temperature (soldering, 10sec)	+245	°C			
Package Thermal Resistance (T <sub>A</sub> =+25℃)	·				
SOP-8, θ <sub>JA</sub>	125°C	:/W			
MSOP-8, θ <sub>JA</sub>	216°C	:/W			
SOT-23-5, θ <sub>JA</sub>	190°C	190°C/W			
ESD Susceptibility	·				
HBM 6KV					
MM	V				

**Note:** Stress greater than those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions outside those indicated in the operational sections of this specification are not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

### **Electrical Characteristics**

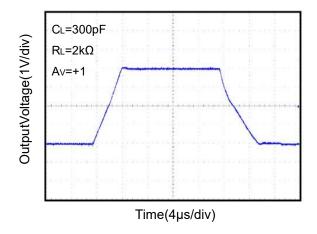
(VS = +5V, VCM = +2.5V, VO = +2.5V, TA = +25 $^{\circ}$ C, unless otherwise noted.)

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
INPUT CHARACTERISTICS					
Input Offset Voltage (VOS)			1	30	μV
Input Bias Current (IB)			20		pA
Input Offset Current (IOS)			10		pA
Common-Mode Rejection Ratio(CMRR)	VCM = 0V to 5V		110		dB
Large Signal Voltage Gain ( AVO)	RL = $10k\Omega$ , VO = $0.3V$ to $4.7V$		145		dB
Input Offset Voltage Drift (ΔVOS/ΔT)			10	50	nV/℃
OUTPUT CHARACTERISTICS					
O. da. d. V. H. a. H. d. (VOII)	RL = 100kΩ to - VS		4.998		V
Output Voltage High (VOH)	RL = 10kΩ to - VS		4.994		V
Outrot Valta and Laur (VOL)	RL = 100kΩ to + VS		2		mV
Output Voltage Low (VOL)	RL = 10kΩ to + VS		5		mV
Short Circuit Limit (ISC)	RL =10Ω to - VS		60		mA
Output Current (IO)			65		mA
POWER SUPPLY					
Power Supply Rejection Ratio (PSRR)	VS = 2.5V to 5.5V		115		dB
Quiescent Current (IQ)	$VO = 0V$ , $RL = 0\Omega$		180		μA
DYNAMIC PERFORMANCE					•
Gain-Bandwidth Product (GBP)	G = +100		1.8		MHz
Slew Rate (SR)	RL = 10kΩ		0.95		V/µs
Overload Recovery Time			0.10		ms
NOISE PERFORMANCE			•		
Voltage Noise (en p-p)	0Hz to 10Hz		0.3		μV <sub>P-P</sub>
Voltage Noise Density (en)	f = 1kHz		38		nV√Hz

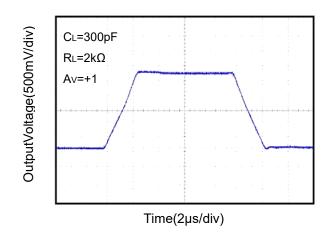


### **Typical Performance characteristics**

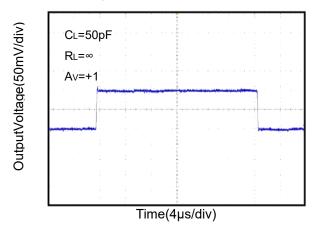




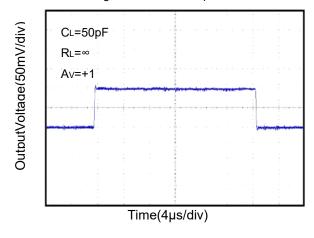
VLarge Signal Transient Response at+2.5V



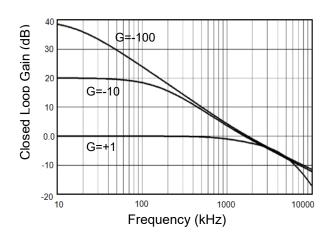
Small Signal Transient Response at +5V



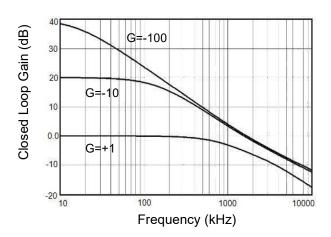
Small Signal Transient Response at +2.5V



Closed Loop Gain vs. Frequency at +5V

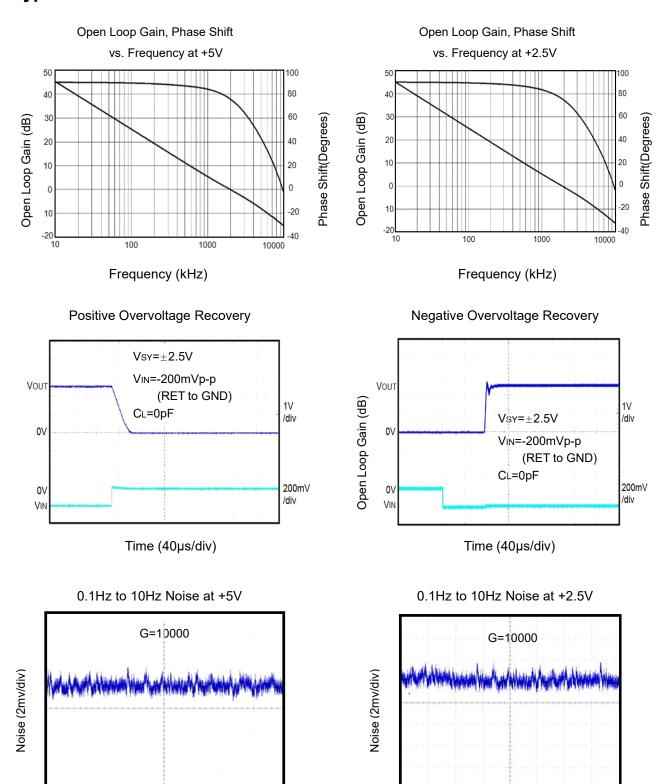


Closed Loop Gain vs. Frequency at +2.5V





### **Typical Performance characteristics**



Time (10s/div)

Time (10s/div)

#### **Application Note Size**

HGV855X series op amps are unity-gain stable and suitable for a wide range of general-purpose applications. The small footprints of the HGV855X series packages save space on printed circuit boards and enable the design of smaller electronic products.

#### **Power Supply Bypassing and Board Layout**

HGV855X series operates from a single 1.8V to 5.5V supply or dual  $\pm 0.9$ V to  $\pm 2.75$ V supplies. For best performance, a 0.1 $\mu$ F ceramic capacitor should be placed close to the VDD pin in single supply operation. For dual supply operation, both VDD and VSS supplies should be bypassed to ground with separate 0.1 $\mu$ F ceramic capacitors.

#### **Low Supply Current**

The low supply current (typical  $180\mu\text{A}$  per channel) of HGV855X series will help to maximize battery life. They are ideal for battery powered systems.

#### **Operating Voltage**

HGV855X series operate under wide input supply voltage (1.8V to 5.5V). In addition, all temperature specifications apply from -40 °C to +85 °C. Most behavior remains unchanged throughout the full operating voltage range. These guarantees ensure operation throughout the single Li-lon battery lifetime.

#### Rail-to-Rail Input

The input common-mode range of HGV855X series extends 100mV beyond the supply rails (VSS-0.1V to VDD+0.1V). This is achieved by using complementary input stage. For normal operation, inputs should be limited to this range.

#### Rail-to-Rail Output

Rail-to-Rail output swing provides maximum possible dynamic range at the output. This is particularly important when operating in low supply voltages. The output voltage of HGV855X series can typically swing to less than 5mV from supply rail in light resistive loads (> $100k\Omega$ ), and 60mV of supply rail in moderate resistive loads ( $10k\Omega$ ).

#### **Capacities Load Tolerance**

The HGV855x family is optimized for bandwidth and speed, not for driving capacitive loads. Output capacitance will create a pole in the amplifier's feedback path, leading to excessive peaking and potential oscillation. If dealing with load capacitance is a requirement of the application, the two strategies to consider are (1) using a small resistor in series with the amplifier's output and the load capacitance and (2) reducing the bandwidth of the amplifier's feedback loop by increasing the overall noise gain. Figure 2. shows a unity gain follower using the series resistor strategy. The resistor isolates the output from the capacitance and, more importantly, creates a zero in the feedback path that compensates for the pole created by the output capacitance.

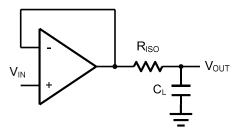


Figure 2. Indirectly Driving a Capacities Load Using Isolation Resistor

The bigger the  $R_{ISO}$  resistor value, the more stable  $V_{OUT}$  will be. However, if there is a resistive load RL in parallel with the capacities load, a voltage divider (proportional to  $R_{ISO}/R_L$ ) is formed, this will result in a gain error.

The circuit in Figure 3 is an improvement to the one in Figure 2. RF provides the DC accuracy by feed-forward the  $V_{IN}$  to  $R_L$ .  $C_F$  and  $R_{ISO}$  serve to counteract the loss of phase margin by feeding the high frequency component of the output signal back to the amplifier's inverting input, thereby preserving the phase margin in the overall feedback loop. Capacities drive can be increased by increasing the value of  $C_F$ . This in turn will slow down the pulse response.

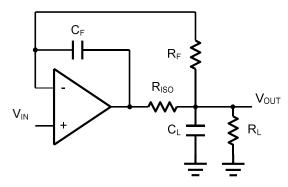


Figure 3. Indirectly Driving a Capacities Load with DC Accuracy

#### **Typical Application Circuits**

#### Differential amplifier

The differential amplifier allows the subtraction of two input voltages or cancellation of a signal common the two inputs. It is useful as a computational amplifier in making a differential to single-end conversion or in rejecting a common mode signal. Figure 4. shown the differential amplifier using HGV855X.

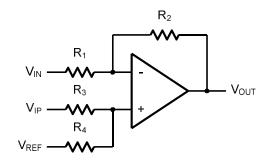


Figure 4. Differential Amplifier

$$V_{OUT} = (\frac{R_1 + R_2}{R_3 + R_4}) \frac{R_4}{R_1} V_{IN} - \frac{R2}{R1} V_{IP} + (\frac{R_1 + R_2}{R_3 + R_4}) \frac{R_3}{R_1} V_{REF}$$

f the resistor ratios are equal (i.e. R1=R3 and R2=R4), then

$$V_{OUT} = \frac{R_2}{R_1} (V_{IP} - V_{IN}) + V_{REF}$$

#### **Low Pass Active Filter**

The low pass active filter is shown in Figure 5. The DC gain is defined by -R2/R1. The filter has a -20dB/decade roll-off after its corner frequency  $fC=1/(2\pi R3C1)$ .

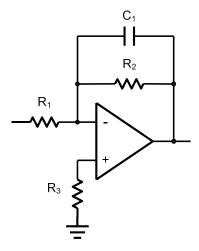


Figure 5. Low Pass Active Filte

#### **Instrumentation Amplifier**

The triple HGV855X can be used to build a three-op-amp instrumentation amplifier as shown in Figure 6. The amplifier in Figure 6 is a high input impedance differential amplifier with gain of R2/R1. The two differential voltage followers assure the high input impedance of the amplifier.

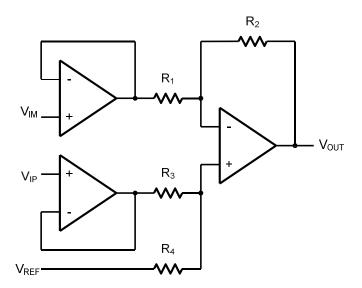
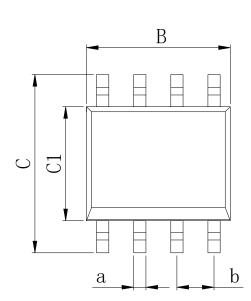


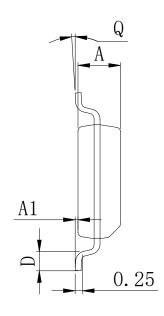
Figure 6. Instrument Amplifier



### **Package Information**

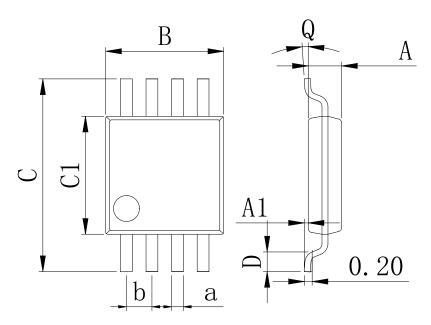
SOP-8





Dimensions In Millimeters(SOP-8)									
Symbol:	Α	A1	В	C	C1	D	Q	а	b
Min:	1.35	0.05	4.90	5.80	3.80	0.40	0°	0.35	1.27 BSC
Max:	1.55	0.20	5.10	6.20	4.00	0.80	8°	0.45	1.21 BSC

MSOP-8

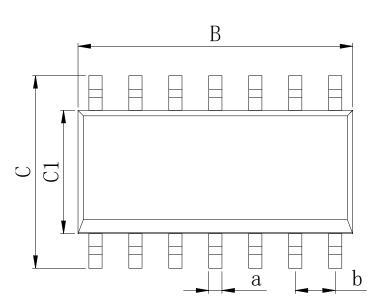


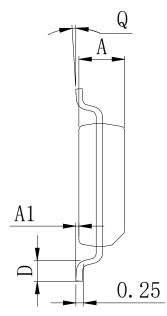
Dimensions In Millimeters(MSOP-8)									
Symbol:	Α	A1	В	С	C1	D	Q	а	р
Min:	0.80	0.05	2.90	4.75	2.90	0.35	0°	0.25	0.65 BSC
Max:	0.90	0.20	3.10	5.05	3.10	0.75	8°	0.35	0.00 BSC



### **Package Information**

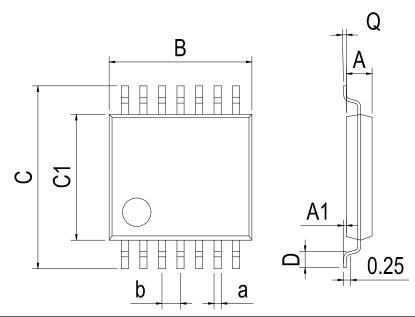
### SOP-14





Dimensions In Millimeters(SOP-14)										
Symbol:	Α	A1	В	С	C1	D	Q	а	b	
Min:	1.35	0.05	8.55	5.80	3.80	0.40	0°	0.35	1.27 BSC	
Max:	1.55	0.20	8.75	6.20	4.00	0.80	8°	0.45	1.27 000	

TSSOP-14

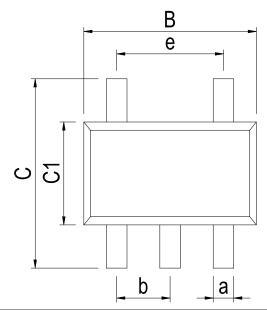


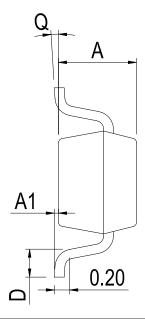
Dimensions In Millimeters(TSSOP-14)										
Symbol:	Α	A1	В	С	C1	D	Q	а	b	
Min:	0.85	0.05	4.90	6.20	4.30	0.40	0°	0.20	0.65 BSC	
Max:	0.95	0.20	5.10	6.60	4.50	0.80	8°	0.25	0.00 BSC	



## **Package Information**

SOT-23-5





Dimensions In Millimeters(SOT-23-5)										
Symbol:	Α	A1	В	С	C1	D	Q	а	b	е
Min:	1.05	0.00	2.82	2.65	1.50	0.30	0°	0.30	0.95 BSC	1.90 BSC
Max:	1.15	0.15	3.02	2.95	1.70	0.60	8°	0.40		



## **Revision History**

DATE	REVISION	PAGE
2020-6-8	New	1-14
2023-7-24	Add Outline Drawing, Update encapsulation type, Update Lead Temperature	1、1、3



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